

ABSTRACT

A ground pad structure for preventing solder extrusion and a semiconductor package having the ground pad structure are disclosed, wherein the ground pad structure has the ground pads located along the circumference of its ground plane be formed in a non-solder mask defined manner. Accordingly, a good grounding quality is maintained, and the occurrence of the electrical bridging among the adjacent conductive traces can be avoided as the extrusion of the molten solder bumps from the ground pads located along the ground pad structure's circumference toward their adjacent conductive traces is effectively prevented.